
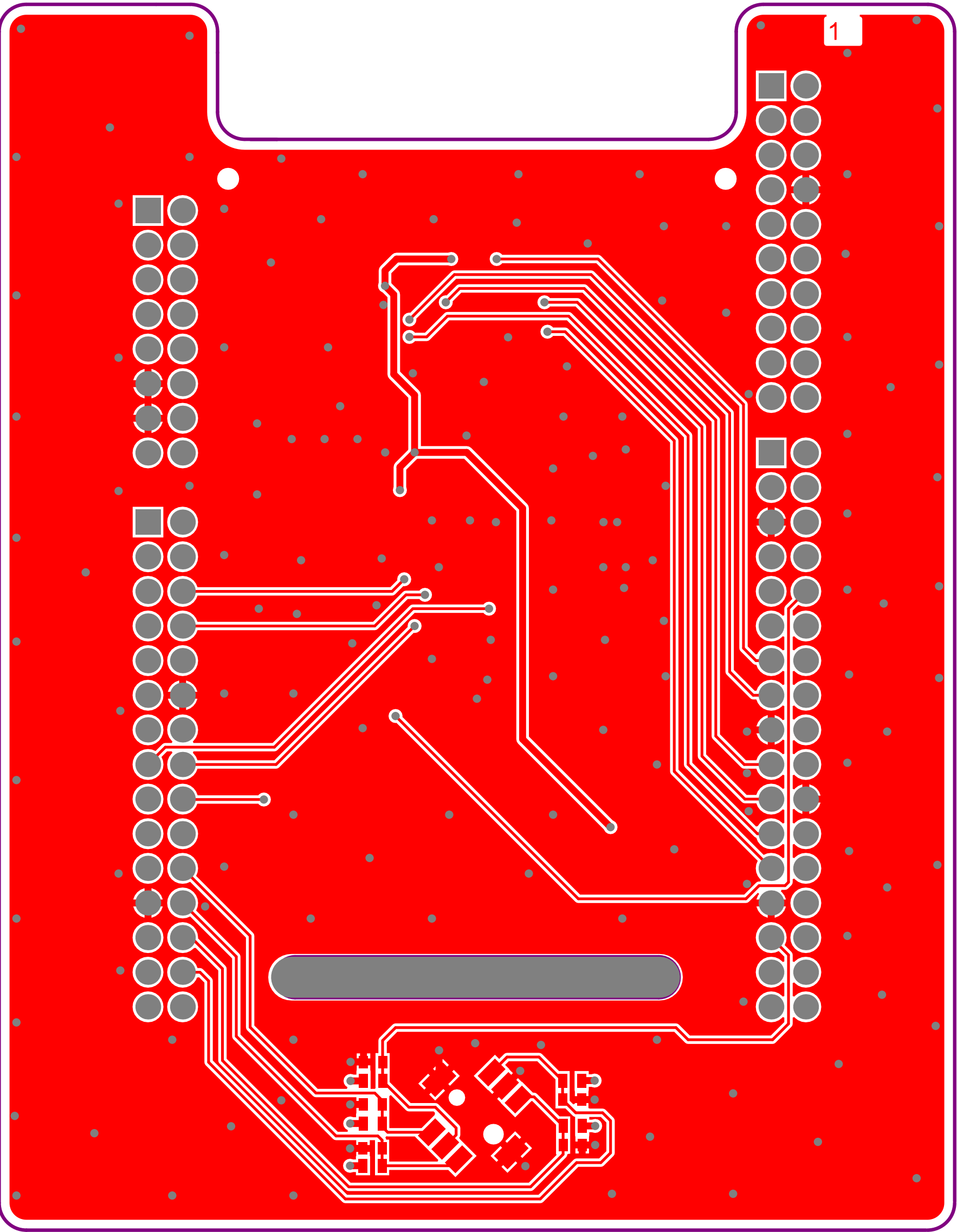



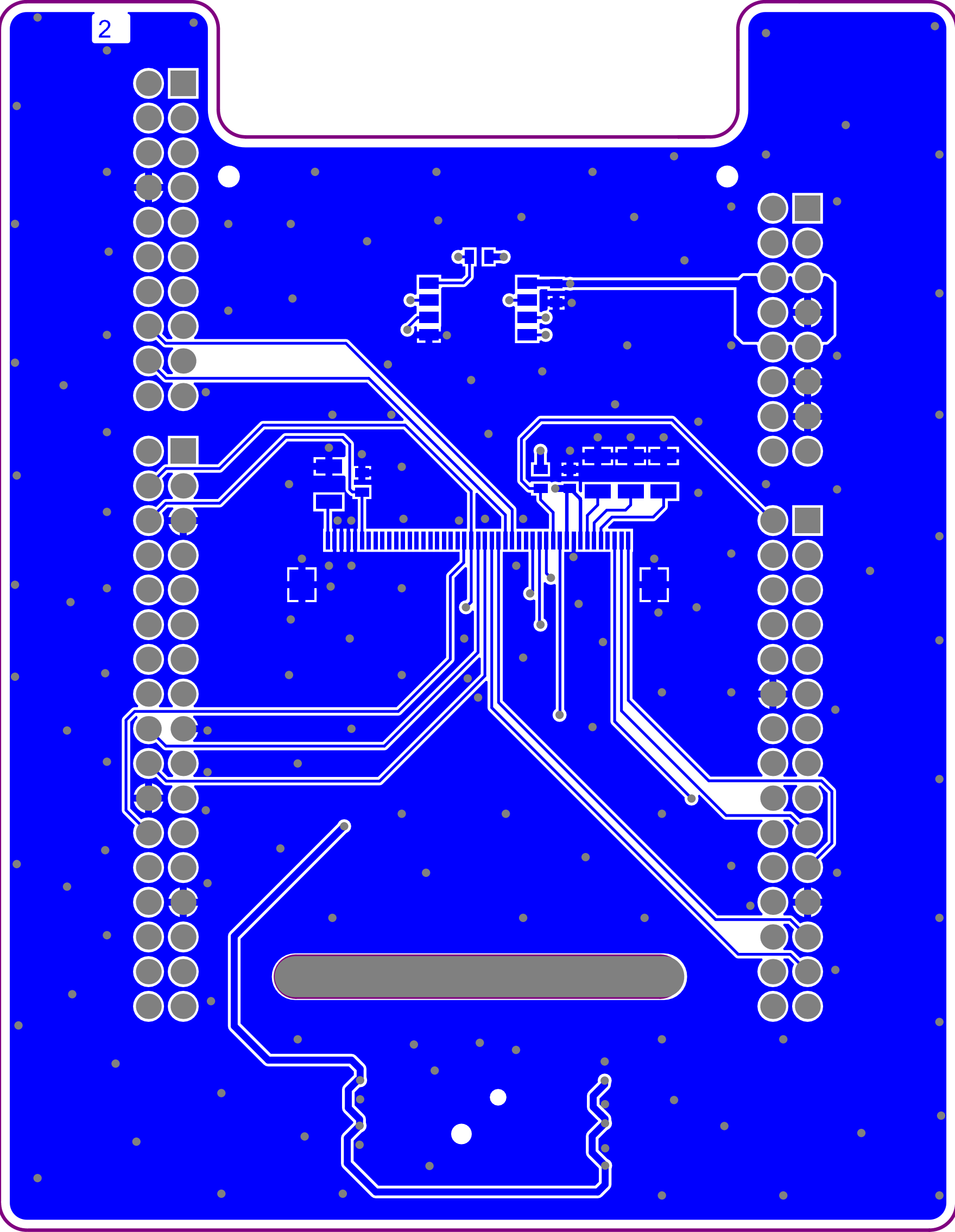
Project: X-NUCLEO-GFX02Z1		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1818	
Date: 01-July-21	Rev: B	


Top Solder

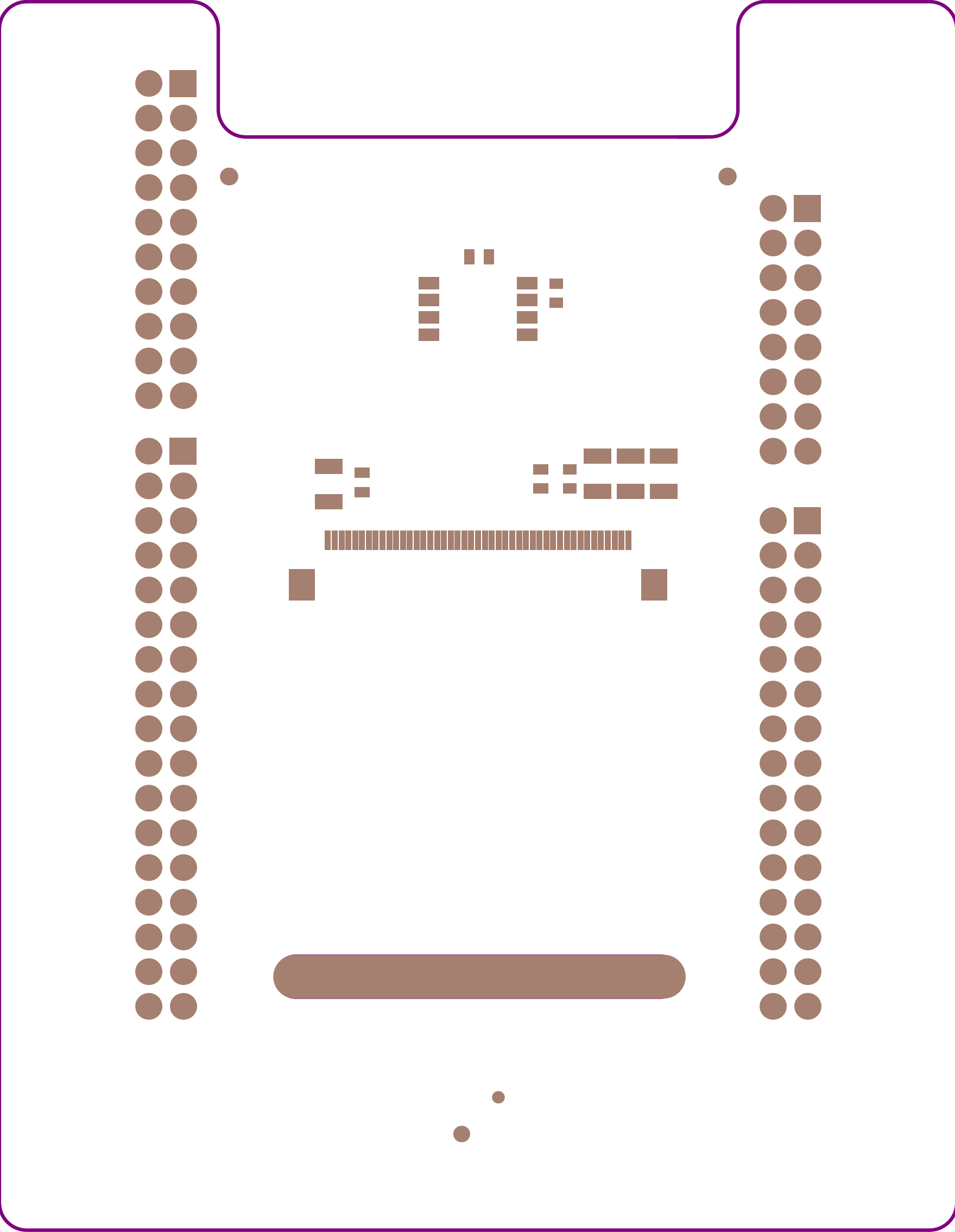
.GTS




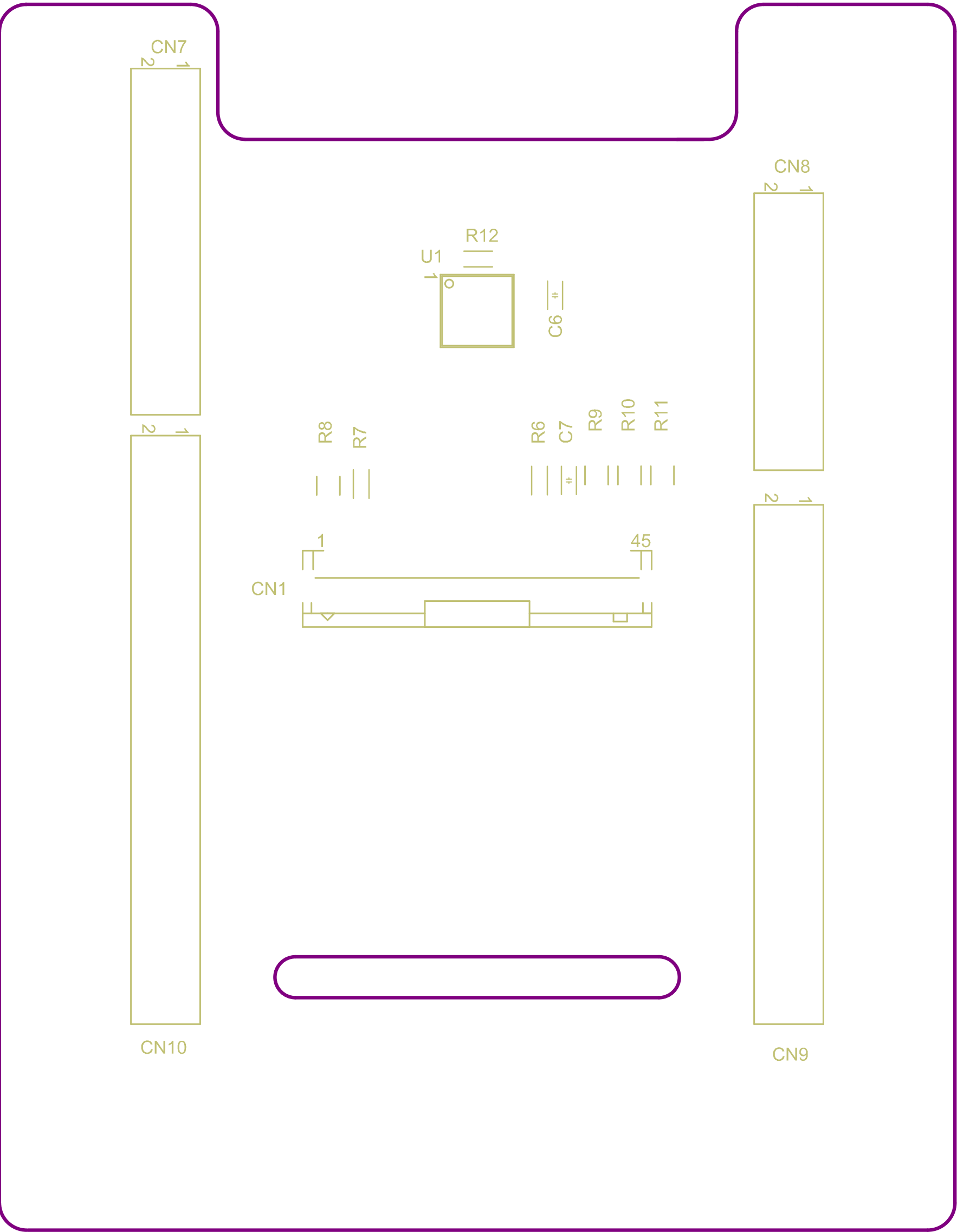
Project: X-NUCLEO-GFX02Z1		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: [No Variations]	Ref: MB1818	
Date: 01-July-21	Rev: B	




Project: X-NUCLEO-GFX02Z1		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB1818	
Date: 01-July-21	Rev: B	



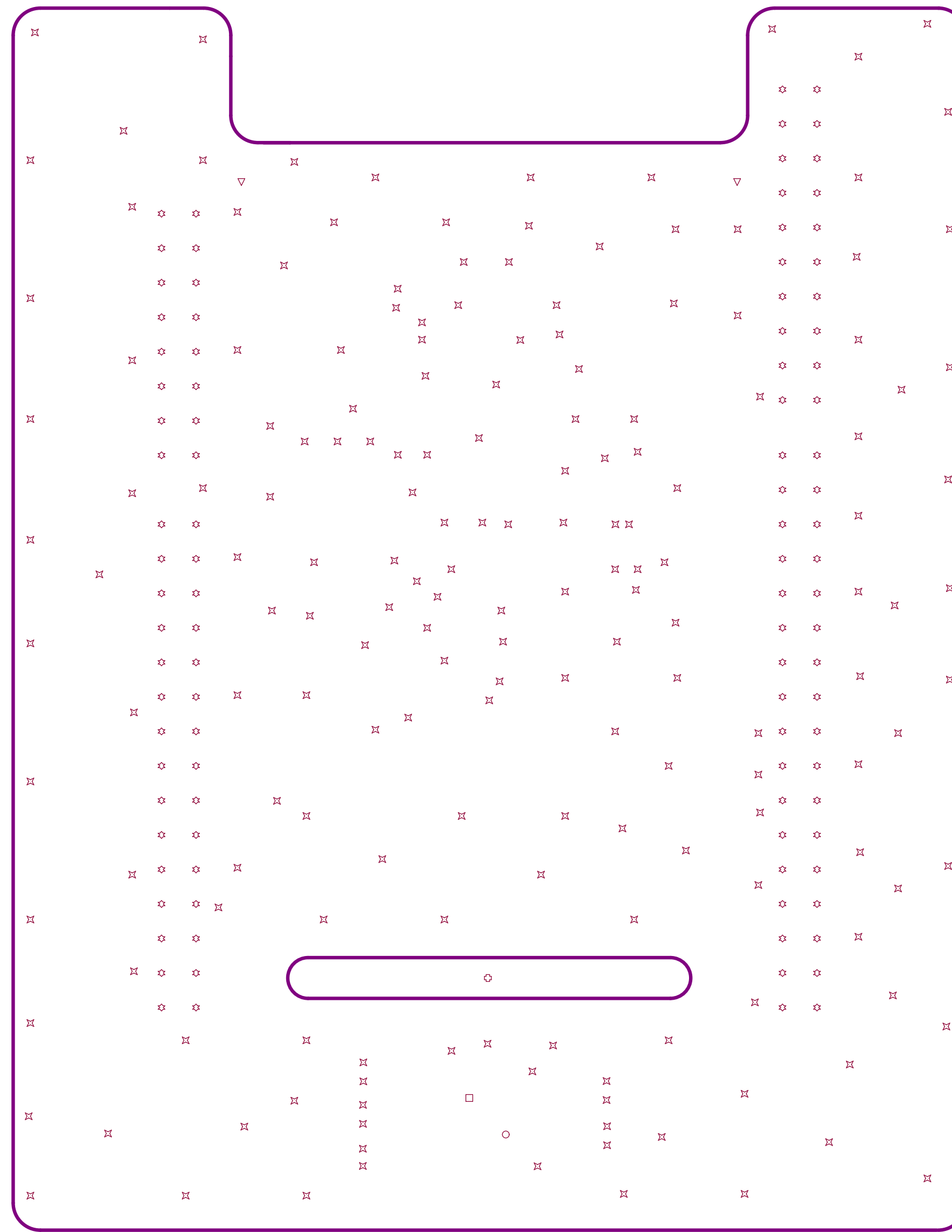
Project: X-NUCLEO-GFX02Z1		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1818	
Date: 01-July-21	Rev: B	



Project: X-NUCLEO-GFX02Z1		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1818	
Date: 01-July-21	Rev: B	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
□	1	31.50mil (0.800mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn80m85p1000			
○	1	43.31mil (1.100mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn110m115p1000			
⊕	1	118.11mil (3.000mm)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r3000_300hn300_3000r100			
▽	2	47.24mil (1.200mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn120m125			
☆	100	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
✕	179	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v61h30m0mx0			
	284 Total										

**Slot definitions :** **Routed Path Length** = Calculated from tool start centre position to tool end centre position.  
**Hole Length** = Routed Path Length + Tool Size = Slot length as defined in the PCB layout




**PCB SPECIFICATIONS :**

- A. MATERIAL : FR-4 ☐ TG-170 ☒ TG-150 ☐ TG-140  
B. MATERIAL FAMILY : N/A  
C. SOLDERMASK COLOR : ☐ GREEN ☐ WHITE ☐ RED ☐ BLACK ☒ Blue ink PANTONE 2955  
D. SILKSCREEN COLOR : ☒ WHITE ☐ YELLOW ☐ BLACK ☐ Blue ink PANTONE 2955  
E. SURFACE FINISH : ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN  
☐ HASL ☐ HASL (PB-FREE) ☐ GOLDEN FINGER  
☒ IMPEDANCE CONTROL : ☒ NO ☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)  
G. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.  
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.  
☒ STACK-UP : SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3
ASPECT-RATIO, AXE Z : 6:1 to 8:1 LEVEL "B"
MINIMUM PARAMETERS
DEFAULT TRACKS : 0.21mm GAPS : 0.21mm

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.59mil	3.5	
1	Top Layer		1.38mil		
	Dielectric 1	FR-4	59.06mil	4.2	
2	Bottom Layer		1.38mil		
	Bottom Solder	Solder Resist	0.59mil	3.5	
	Bottom Overlay				

Project: X-NUCLEO-GFX02Z1		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1818	
Date: 01-July-21	Rev: B	